

In the Claims:

Please cancel Claims 8, 10, 12-16 and 31-36, without prejudice, and amend

Claims 1, 3 and 5 as follows:

Sub C1
B4

1. (Once Amended) An embedded electroconductive layer comprising:
a depressed part formed in an insulating film on a substrate;
a barrier layer covering said depressed part;
a metal growth promoting layer on said barrier layer, said metal growth promoting layer being made of a material different from that of said barrier layer; and
an electroconductive layer embedded in said depressed part via said barrier layer and said metal growth promoting layer.

Sub C2
B5

3. (Twice Amended) The embedded electroconductive layer according to claim 1 wherein said metal growth promoting layer is a TiN layer containing oxygen at a lower concentration than said barrier layer.

Sub C2
B6

5. (Once Amended) An embedded electroconductive layer comprising:
a depressed part formed in an insulating layer on a substrate;
a ground layer containing oxygen at a high concentration in the lower part thereof and at a low concentration in the upper part thereof due to removal of oxygen